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October 2014

FDMS7670AS

N-Channel PowerTrench[®] SyncFETTM 30 V, 42 A, 3 m Ω

Features

- Max $r_{DS(on)}$ = 3.0 m Ω at V_{GS} = 10 V, I_D = 21 A
- Max $r_{DS(on)}$ = 3.2 m Ω at V_{GS} = 7 V, I_D = 19 A
- \blacksquare Advanced Package and Silicon combination for low $r_{\mbox{DS}(\mbox{on})}$ and high efficiency
- SyncFET Schottky Body Diode
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

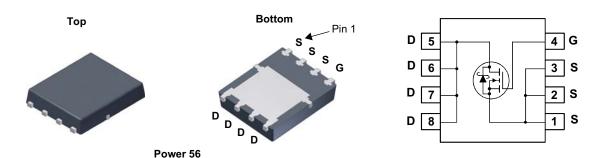


General Description

The FDMS7670AS has been designed to minimize losses in power conversion application. Advancements in both silicon and package technologies have been combined to offer the lowest $r_{\text{DS}(\text{on})}$ while maintaining excellent switching performance. This device has the added benefit of an efficient monolithic Schottky body diode.

Applications

- Synchronous Rectifier for DC/DC Converters
- Notebook Vcore/ GPU low side switch
- Networking Point of Load low side switch
- Telecom secondary side rectification



MOSFET Maximum Ratings T_C = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V _{DS}	Drain to Source Voltage			30	V
V _{GS}	Gate to Source Voltage		(Note 4)	±20	V
	Drain Current -Continuous (Package limited)	T _C = 25 °C		42	
	-Continuous (Silicon limited)	T _C = 25 °C		113	
ID	-Continuous	T _A = 25 °C	(Note 1a)	22	A
	-Pulsed			150	
dv/dt	MOSFET dv/dt			1.8	V/ns
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	98	mJ
D	Power Dissipation	T _C = 25 °C		65	w
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	vv
T _J , T _{STG}	Operating and Storage Junction Temperature R	ange		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.9	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS7670AS	FDMS7670AS	Power 56	13 "	12 mm	3000 units

Electrical Characteristics T_A = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	I _D = 1 mA, V _{GS} = 0 V	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, referenced to 25 °C		14		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			500	μΑ
I _{GSS}	Gate to Source Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA

On Characteristics (Note 2)

-5		mV/°C
2.4	3.0	
2.5	3.2	mΩ
3.0	3.5 3.8	1115.2
3.0		
300		S
	2.4 2.5 3.0 3.0	2.4 3.0 2.5 3.2 3.0 3.5 3.0 3.8

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 15 V V - 0 V	3175	4225	pF
C _{oss}	Output Capacitance	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	1175	1565	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11/12	110	165	pF
R_q	Gate Resistance		1.3	2.6	Ω

Switching Characteristics

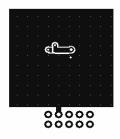
t _{d(on)}	Turn-On Delay Time		14	25	ns
t _r	Rise Time	V _{DD} = 15 V, I _D = 21 A,	6	12	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{GEN} = 6 Ω	35	56	ns
t _f	Fall Time		5	10	ns
Q_{g}	Total Gate Charge	V _{GS} = 0 V to 10 V	47	66	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 15 \text{ V}$	22	31	nC
Q _{gs}	Gate to Source Gate Charge	I _D = 21 A	8.5		nC
Q _{gd}	Gate to Drain "Miller" Charge		4.9		nC

Drain-Source Diode Characteristics

\/-	V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2 \text{ A}$ (Note 2)	0.43	0.7	V
\vs	SD	Source to Drain Diode Forward Voltage	$V_{GS} = 0 V, I_S = 21 A$ (Note 2)	0.75	1.2	
t _{rr}		Reverse Recovery Time	I _F = 21 A, di/dt = 300 A/ μs	35	56	ns
Q_r	r	Reverse Recovery Charge		41	67	nC

Notes:

^{1.} R_{BJA} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{BJC} is guaranteed by design while R_{BCA} is determined by the user's board design.



a. 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



 b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%.
- 3. E_{AS} of 98 mJ is based on starting T_J = 25 $^{\circ}$ C, L = 1 mH, I_{AS} = 14 A, V_{DD} = 27 V, V_{GS} = 10 V. 100% test at L = 0.3 mH, I_{AS} = 21 A.
- 4. As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

Typical Characteristics T_{.1} = 25 °C unless otherwise noted

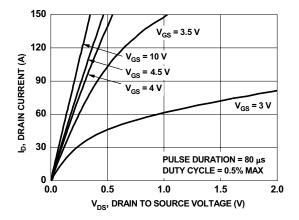


Figure 1. On-Region Characteristics

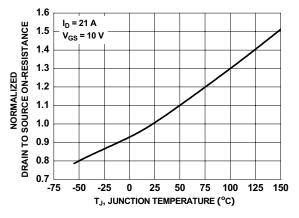


Figure 3. Normalized On-Resistance vs Junction Temperature

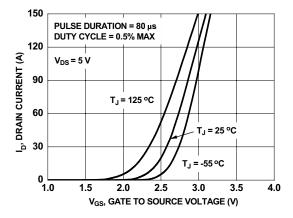


Figure 5. Transfer Characteristics

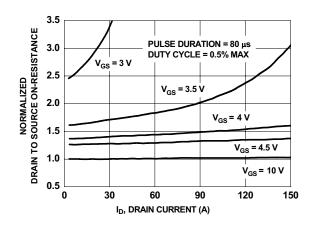


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

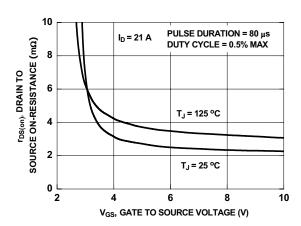


Figure 4. On-Resistance vs Gate to Source Voltage

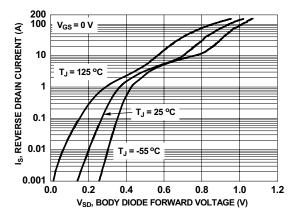


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted

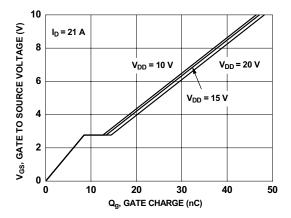


Figure 7. Gate Charge Characteristics

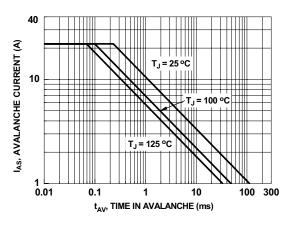


Figure 9. Unclamped Inductive Switching Capability

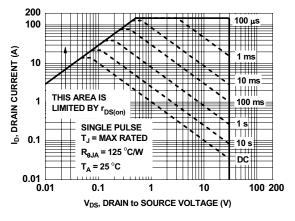


Figure 11. Forward Bias Safe Operating Area

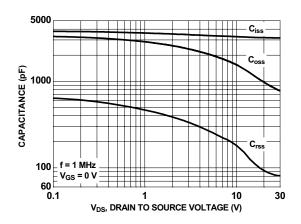


Figure 8. Capacitance vs Drain to Source Voltage

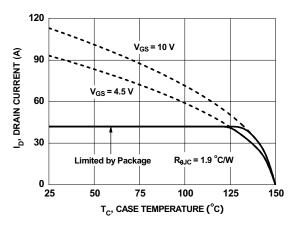


Figure 10. Maximum Continuous Drain Current vs Case Temperature

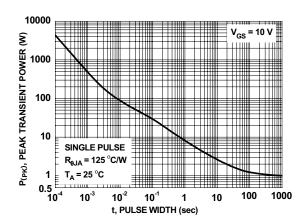


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

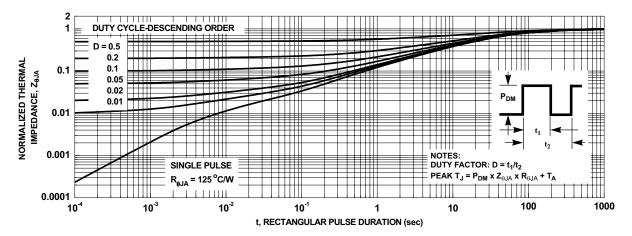


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

Typical Characteristics (continued)

SyncFET Schottky body diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MoSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 14 shows the reverses recovery characteristic of the FDMS7670AS.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

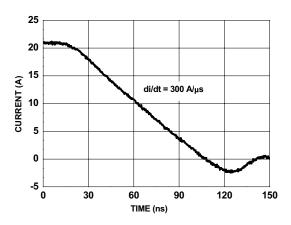


Figure 14. FDMS7670AS SyncFET body diode reverse recovery characteristic

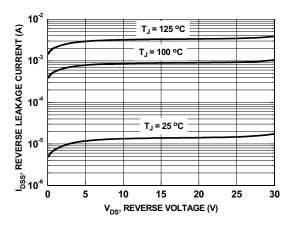


Figure 15. SyncFET body diode reverses leakage versus drain-source voltage



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